3GPP TSG GERAN#1
Seattle, WA
27 August- 1 September 2000

GP (00)0432

Agenda Item:	**7.5**
Source:	**Siemens**
To:	**GERAN#1**
Title:	**Proposed WI "Low Chip Rate TDD Interworking with GERAN "**
Document for:	**Approval**

Work Item Description

Title

Low Chip Rate TDD Inter-working with GERAN

1 TSG GERAN Work Area

X	Radio Access
	Core Network
	Services

2 Linked work items

Low Chip Rate TDD physical layer
Low chip rate TDD Layer 2 and Layer 3 protocol aspects
Low chip rate TDD UTRAN architecture aspects
Low chip rate TDD: Smart Antenna
Low chip rate TDD: RF Radio Transmission/Reception, System Performance Requirements and Conformance Testing
Low chip rate TDD UE radio access capabilities

3 Justification

The integration of TDD low chip rate (1.28 Mcps) option in Release 2000 was discussed and approved in RAN#6. The work plan of the integration of low chip rate TDD in R00 was discussed in RAN#7. As a feature, the low chip rate TDD is sub-divided into several building blocks via the email discussion. Although the handover and the Cell Selection / Reselection to the low chip rate TDD is very similar to the handover and the Cell Selection / Reselection to the UTRA TDD (3.84 Mcps), there are some differences ,e.g. modification of the system broadcast and measurement report, which should be described and clarified. Basically, most of them were originated from the differences of physical layer between low chip rate TDD and UTRA TDD (3.84 Mcps). This paper is to describe one of the low chip rate TDD building blocks – inter-working with GERAN.

4 Objective

The technical objective of this work item is to complete the GSM functionality handover and Cell Selection / Reselection to UTRA FDD and 3.84 Mcps TDD with the adaptations to the handover and Cell Selection / Reselection to the low chip rate UTRA TDD. This work will affect the specifications for working group on TSG GERAN WG1 and WG2.

- It includes the following work tasks:
  - UE measurement report procedures
  - System Broadcast
  - Intersystem handover procedures

Task	Planned Start	Planned Finish
Prepare technical inputs	08/2000	11/2000
Drafting, change request and possible new specs	08/2000	11/2000
Possible corrections	11/2000	01/2001

5 Service Aspects

None

6 MMI-Aspects

None

7 Charging Aspects

None

8 Security Aspects

None

9 Impacts

Affects:	USIM	ME	AN	CN	Others
Yes		X	X		
No	X			X	X
Don't know					

10 Expected Output and Time scale (to be updated at each plenary)

New specifications						
Spec No.	Title	Prime rsp. WG	2ndary rsp. WG(s)	Presented for information at plenary#	Approved at plenary#	Comments

Affected existing specifications				
Spec No.	CR	Subject	Approved at plenary#	Comments
TS44.018		Radio Resource Control Protocoll	TSG-GERAN#2	
TS44.060		Radio Link Control / Medium Access Control Protocol	TSG-GERAN#2	
TS45.002		Multiplexing and multiple access on the radio path	TSG-GERAN#2	
TS45.008		Radio subsystem link control	TSG-GERAN#2	
TS48.008		MSC-BSS interface Layer 3 specification	TSG-GERAN#2	
TS48.058		BSC-BTS interface Layer 3 specification	TSG-GERAN#2	
TS24.008				

11 Work item rapporteur

Mr. Kenneth Isaacs (Siemens)

12 Work item leadership

TSG-GERAN

13 Supporting Companies

Ericsson, IDC, Siemens, Motorola

14 Classification of the WI (if known)

	Feature (go to 14a)

X	Building Block (go to 14b)
	Work Task (go to 14c)

14a The WI is a Feature: List of building blocks under this feature

(list of Work Items identified as building blocks)

14b The WI is a Building Block: parent Feature

low chip rate TDD

14c The WI is a Work Task: parent Building Block

(one Work Item identified as a building block)